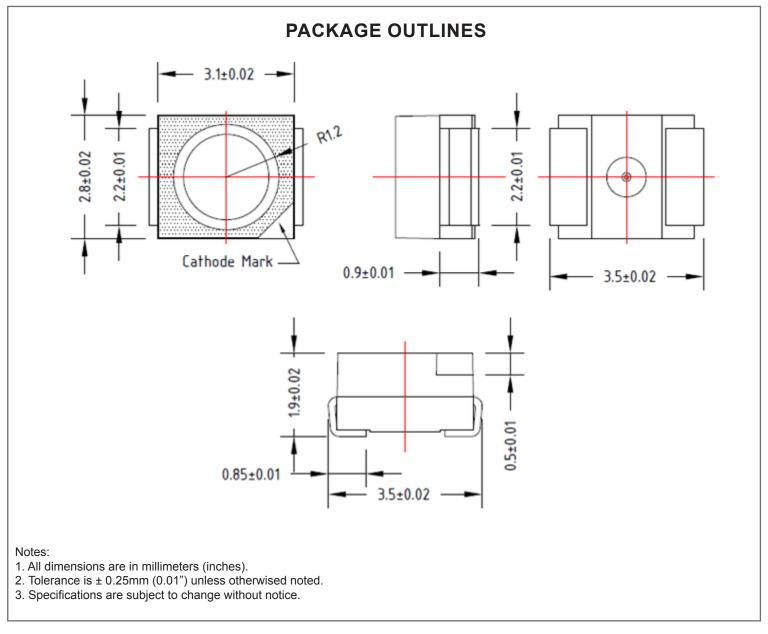


SPECIFICATION

CSP1311W3C



| Part Number | Chip Material | Color of Emission | Lens Type | Viewing Angle |
|-------------|---------------|-------------------|-------------|---------------|
| CSP1311W3C | InGaN | White | Water Clear | 120° |





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

| Parameter | Symbol | Max Rating | Unit |
|--|--------|--------------------------|------|
| Forward Current | lF | 30 | mA |
| Power Dissipation | Pd | 100 | mW |
| Reverse Voltage | VR | 5 | V |
| Operating Temperature Range | Тор | -30~+85 | °C |
| Storage Temperature Range | Тѕтс | -40~+100 | °C |
| Peak Pulsing Current (1/8 duty f = 1KHz) | lfp | 100 | mA |
| Soldering Temperature | Tsol | Max 265°C for 10 sec Max | |

OPTICAL-ELECTRICAL CHARACTERISTICS

Value Parameter Symbol **Test Condition** Unit Min Тур Max Luminous Intensity Iv IF = 20mA1800 2300 Mcd _ Forward Voltage IF = 20mAV VF 3.1 3.5 _ Viewing Angle at 50% Iv $2\theta 1/2$ IF = 20mA120 _ Deg _ **Chromaticity Coordinate** IF = 25mAХ 0.31 _ _ _ **Chromaticity Coordinate** Y IF = 25mA0.32 _ _ -

*Tolerance of viewing angle: -10 / +5 deg.



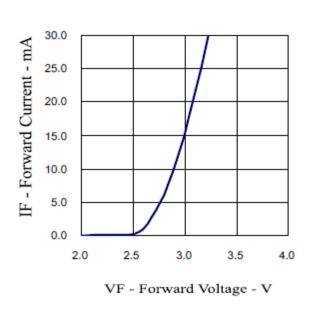
ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com

(TA=25°C)

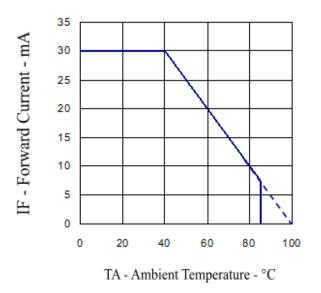


OPTICAL CHARACTERISTIC CURVES

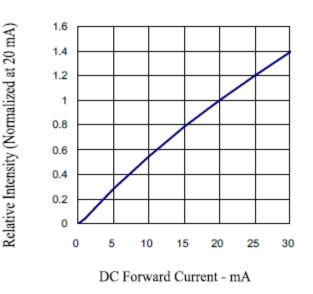
Forward Current vs. Forward Voltage



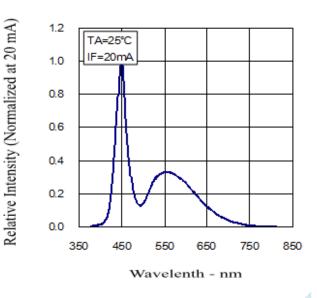
Forward Current vs. Ambient Temperature



Relative Intensity vs. Forward Current



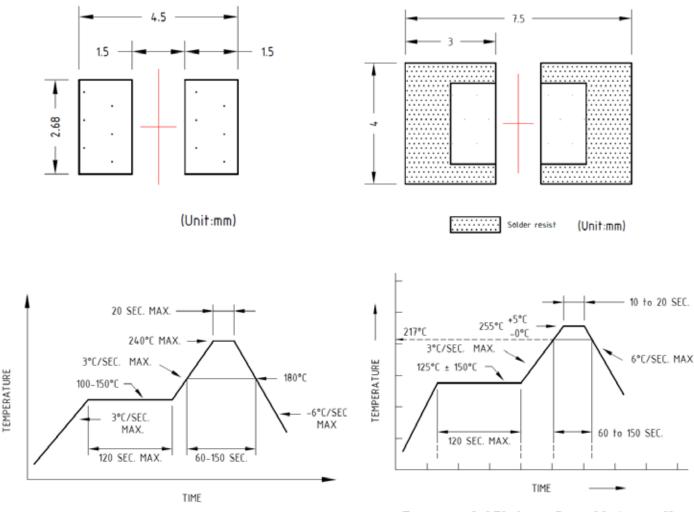
Relative Intensity vs. Wavelength



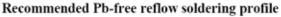




SOLDERING CONDITIONS



Recommended reflow soldering profile



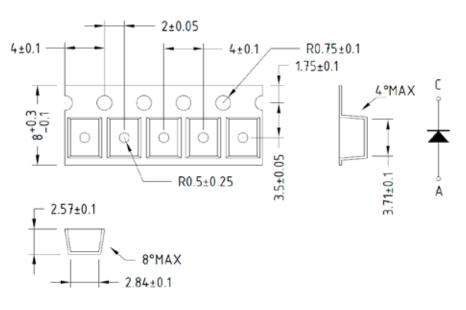
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do no put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.





PACKAGING SPECIFICATION

Tape Dimension



Tape Leader and Trailer Dimension

